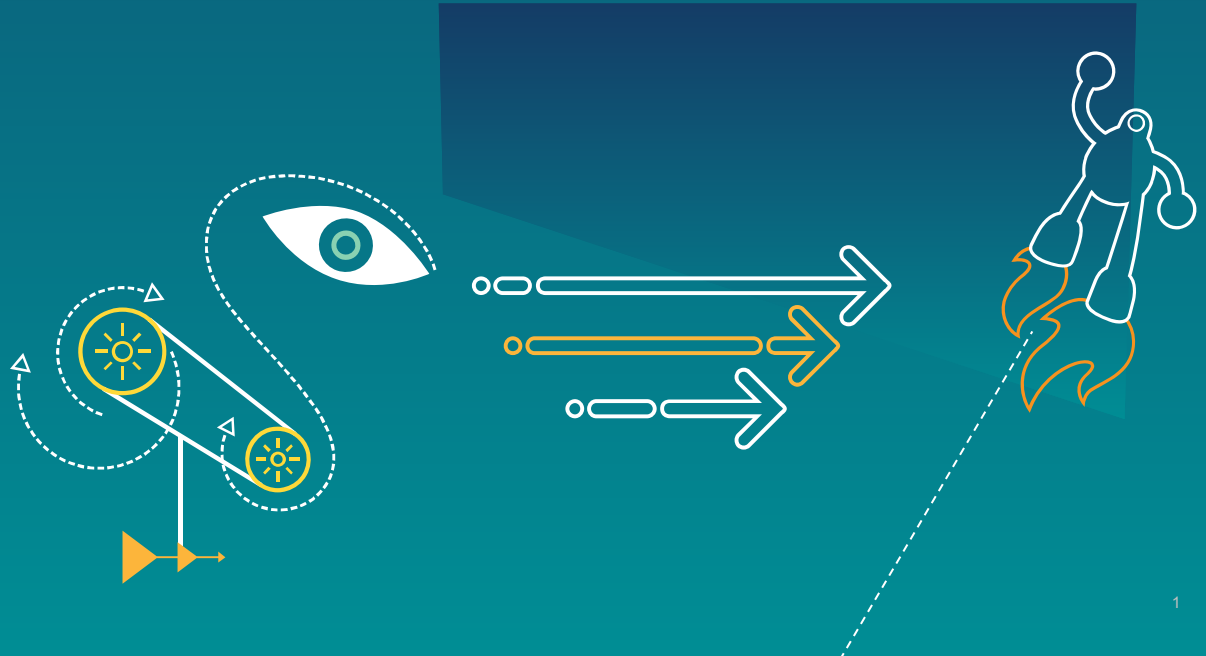


Speaker name
Job title, date, legal entity

layout feedback




April 19th



Stackup change

We switched to different PWB manufacturer.

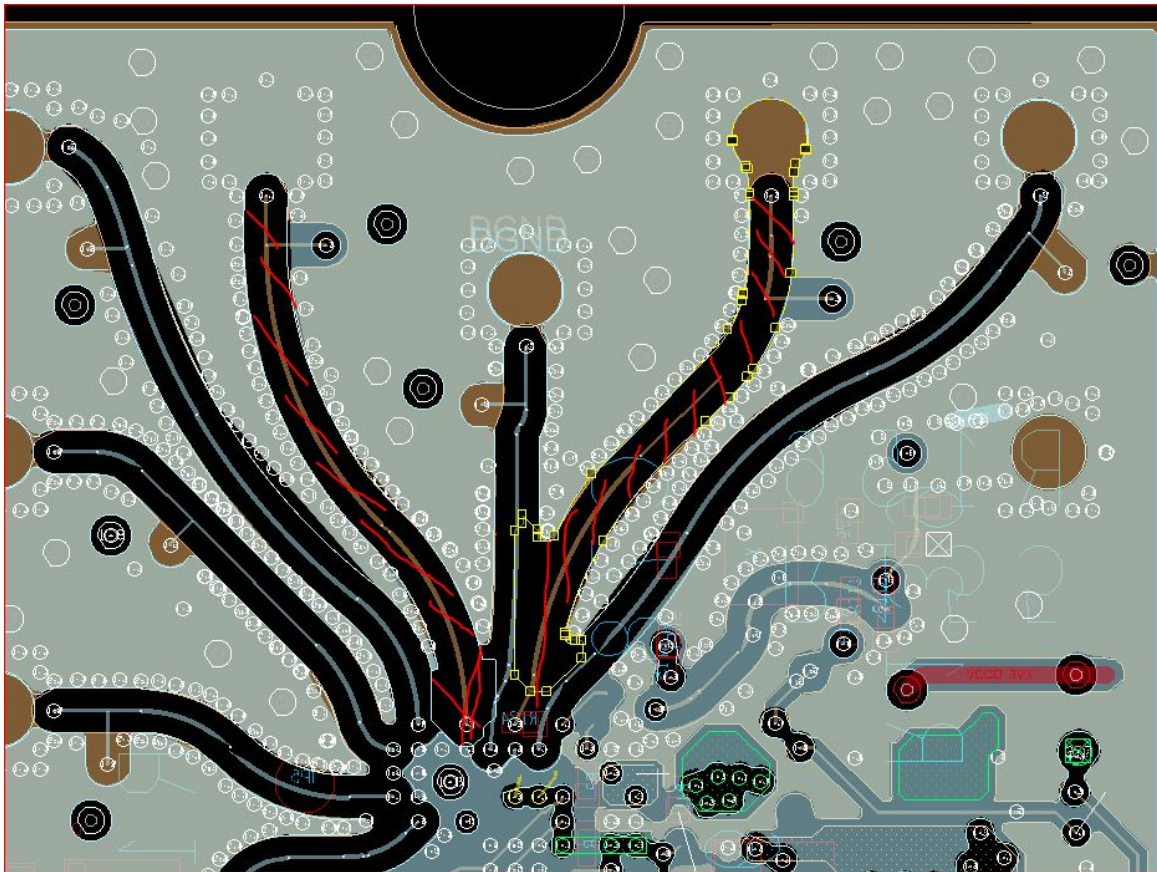
Need to update all the control impedance traces in all the layers

Waivers - Customer approval of stackup includes approval of:		Notes / Comments:																			
		1- Please include approved stackup with final data set.																			
		 Stacked micro vias: Layers 1-2, 2-3, 7-6 and 8-7 to be copper filled  Buried vias: Layers 3-6 will be non conductive epoxy filled.  Indicates a Dummy Sub. (TTM's internal use only)																			
Layer #	Nominal Thick.	Tolerance	LYR #	Single Ended Model					LYR #	Differential Model						K					
				Org. L/W	A/W L/W	Fin. L/W	Ref. Plane	Calc. Imp.		Org. L/W	Org. space	A/W L/W	A/W space	Fin. L/W	Fin. space	Ref. Plane	Calc. Imp.	Factor			
																Zs	Ks	ZD	KD		
1 MP	43.18		1	77		77	2	50	1	72	250			72	250	2	100				
	53.34								1	100	180			100	180	2	85				
2 MP	16.51																				
	60.96																				
3 S	26.67		3	70		70	2 & 4	50	3	70	250			70	250	2 & 4	100				
	113.03								3	95	180			95	180	2 & 4	85				
4 MP	16.51																				
	101.60																				
5 MP	16.51																				
	113.03																				
6 S	26.67		6	70		70	5 & 7	50	6	70	250			70	250	5 & 7	100				
	60.96								6	95	180			95	180	5 & 7	85				
7 MP	16.51																				
	53.34																				
8 MP	43.18		8	77		77	7	50	8	72	250			72	250	7	100				
Thickness After plating			762.00		not including solder mask				Units		Um										
Target Thickness			0.8 ± 0.100		over Plating				Impedance Tolerance		(SE) +/- 10%		(DIFF) +/- 15%								

XIF Trace on Layer 3 – fill Layer 2

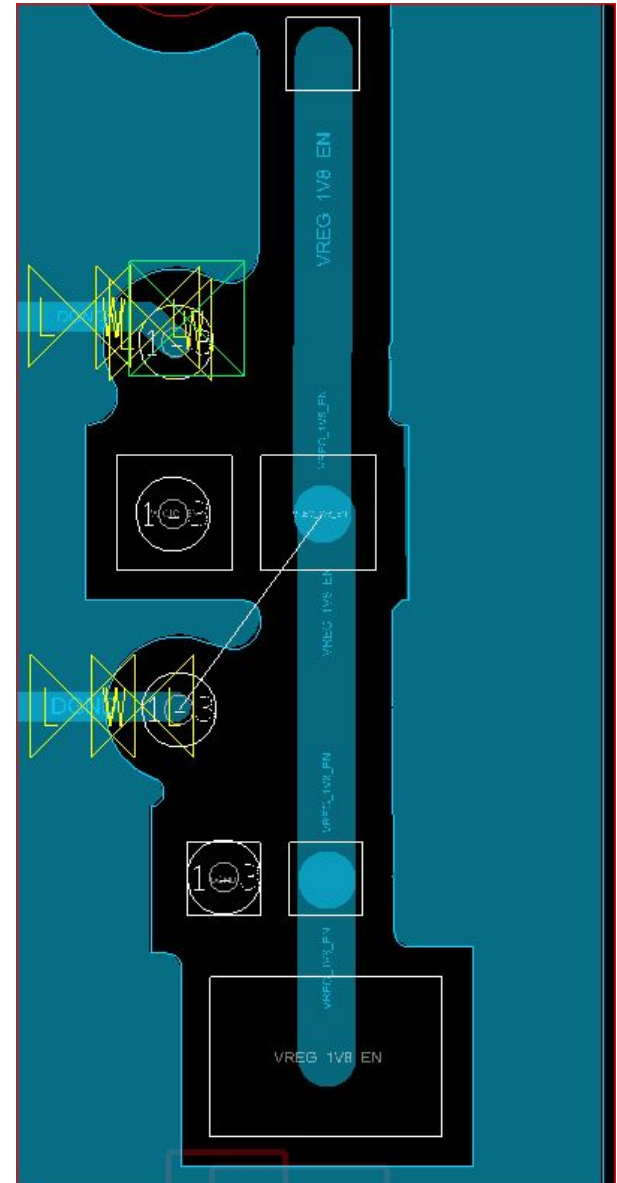
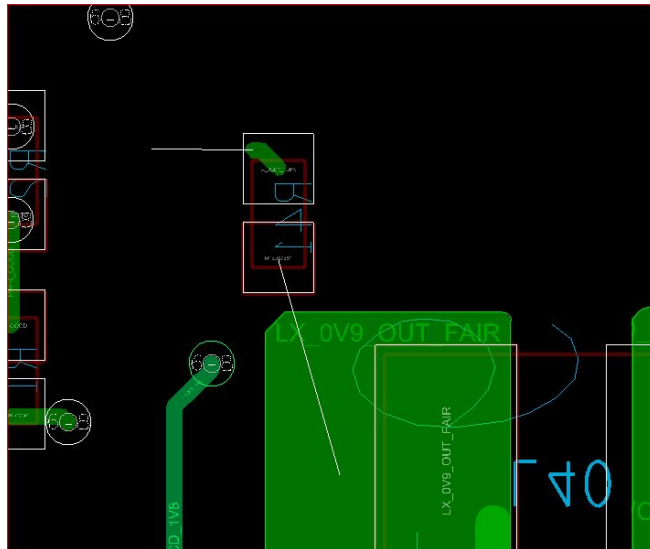
Route on L3 with L2 full reference above (ref layers L2 and L4)

Ned stackup allow this new routing



Netlist change

Fix open nets – I removed several components



Silk screen

Make the bottom side label smaller to fit the

